

Single Phase Half Controlled Bridges

PSBH 75

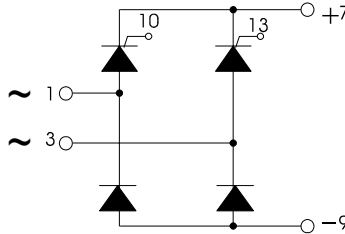
$$\begin{matrix} I_{TAVM} \\ V_{RRM} \end{matrix}$$

= 74 A
= 400-1600 V

Preliminary Data Sheet

V_{RSM} V_{DSM}	V_{RRM} V_{DRM}	Type
500	400	PSBH 75/04
900	800	PSBH 75/08
1300	1200	PSBH 75/12
1500	1400	PSBH 75/14
*1700	*1600	PSBH 75/16

* Delivery on request



Symbol	Test Conditions		Maximum Ratings		
I_{TAVM}	T _C = 85 °C	per module	74	A	
I_{FSM}, I_{TSM}	T _{VJ} = 45 °C	t = 10 ms (50 Hz), sine	1150	A	
	V _R = 0	t = 8.3 ms (60 Hz), sine	1230	A	
	T _{VJ} = T _{VJM}	t = 10 ms (50 Hz), sine	1000	A	
	V _R = 0	t = 8.3 ms (60 Hz), sine	1070	A	
∫ i² dt	T _{VJ} = 45 °C	t = 10 ms (50 Hz), sine	6600	A ² s	
	V _R = 0	t = 8.3 ms (60 Hz), sine	6280	A ² s	
	T _{VJ} = T _{VJM}	t = 10 ms (50 Hz), sine	5000	A ² s	
	V _R = 0	t = 8.3 ms (60 Hz), sine	4750	A ² s	
(di/dt)_{cr}	T _{VJ} = T _{VJM}	repetitive, I _T = 150 A	100	A/μs	
	f = 50Hz, t _p = 200μs				
	V _D = 2/3 V _{DRM}				
	I _G = 0.3 A	non repetitive, I _T = I _{TAVM}	500	A/μs	
	di _G /dt = 0.3 A/μs				
(dv/dt)_{cr}	T _{VJ} = T _{VJM}	V _{DR} = 2/3 V _{DRM}	1000	V/μs	
	R _{GK} = ∞, method 1 (linear voltage rise)				
P_{GM}	T _{VJ} = T _{VJM}	t _p = 30μs	10	W	
	I _T = I _{TAVM}	t _p = 300μs	5	W	
P_{GAVM}			0.5	W	
V_{RGM}			10	V	
T_{VJ}			-40 ... + 125	°C	
T_{VJM}			125	°C	
T_{stg}			-40 ... + 125	°C	
V_{ISOL}	50/60 HZ, RMS	t = 1 min	2500	V ~	
	I _{ISOL} ≤ 1 mA	t = 1 s	3000	V ~	
M_d	Mounting torque	(M5)	5	Nm	
	Terminal connection torque	(M3)	1.5	Nm	
		(M5)	5	Nm	
Weight	typ.		220	g	

Features

- Package with screw terminals
- Isolation voltage 3000 V~
- Planar glasspassivated chips
- Low forward voltage drop
- UL registered E 148688

Applications

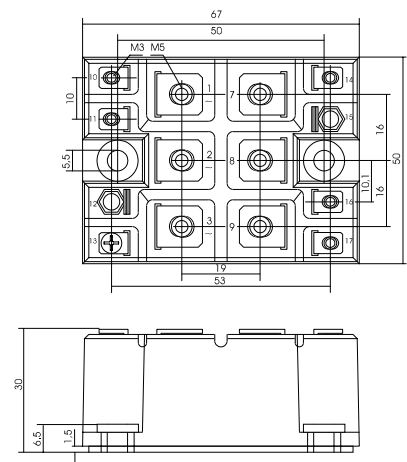
- Heat and temperature control for industrial furnaces and chemical processes
- Lighting control
- Motor control
- Power converter

Advantages

- Easy to mount with two screws
- Space and weight savings
- Improved temperature and power cycling capability
- High power density

Package, style and outline

Dimensions in mm (1mm = 0.0394")



Symbol	Test Conditions		Characteristic Value	
I _D , I _R	T _{VJ} = T _{VJM} , V _R = V _{RRM} , V _D = V _{DRM}		≤	5 mA
V _T	I _T = 150A, T _{VJ} = 25°C		≤	1.57 V
V _{TO}	For power-loss calculations only (T _{VJ} = T _{VJM})			0.85 V
r _T				6 mΩ
V _{GT}	V _D = 6V	T _{VJ} = 25°C	≤	1.0 V
		T _{VJ} = -40°C	≤	1.6 V
I _{GT}	V _D = 6V	T _{VJ} = 25°C	≤	100 mA
		T _{VJ} = -40°C	≤	150 mA
V _{GD}	T _{VJ} = T _{VJM}	V _D = 2/3 V _{DRM}	≤	0.2 V
I _{GD}	T _{VJ} = T _{VJM}	V _D = 2/3 V _{DRM}	≤	5 mA
I _L	T _{VJ} = 25°C, t _p = 10μs		≤	200 mA
	I _G = 0.3A, di _G /dt = 0.3A/μs			
I _H	T _{VJ} = 25°C, V _D = 6V, R _{GK} = ∞		≤	150 mA
t _{gd}	T _{VJ} = 25°C, V _D = ½ V _{DRM}		≤	2 μs
	I _G = 0.3A, di _G /dt = 0.3A/μs			
t _q	T _{VJ} = T _{VJM} , I _T = 20A, t _p = 200μs, V _R = 100V			150 μs
	-di/dt = 10A/μs, dv/dt = 15V/μs, V _D = 2/3 V _{DRM}			
R _{thJC}	per thyristor; sine 180°el			0.66 K/W
	per module			0.165 K/W
R _{thJK}	per thyristor; sine 180° el			0.93 K/W
	per module			0.2325 K/W
d _s	Creeping distance on surface			8.0 mm
d _A	Creeping distance in air			4.5 mm
a	Max. allowable acceleration			50 m/s ²

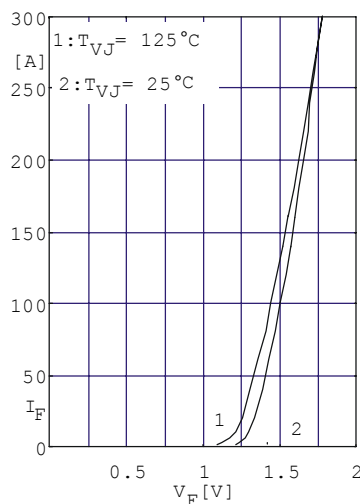


Fig. 1 Forward current vs. voltage drop per diode or thyristor

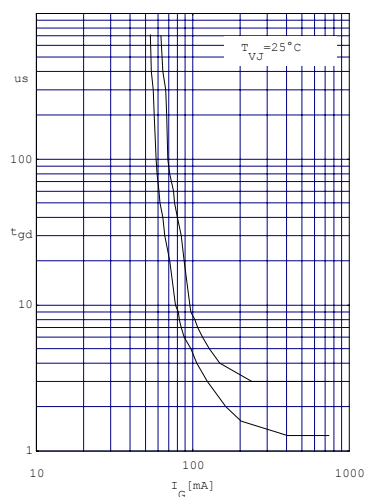


Fig. 2 Gate trigger delay time

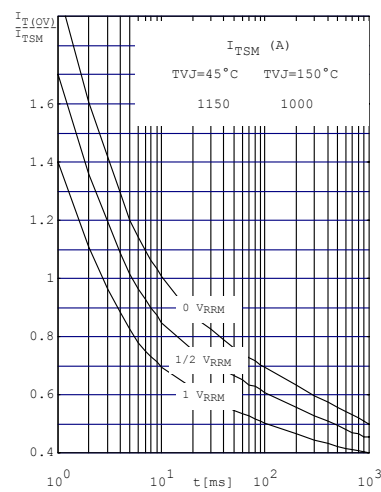


Fig. 3 Surge overload current per diode (or thyristor) I_{FSM} , I_{TSM} : Crest value t : duration

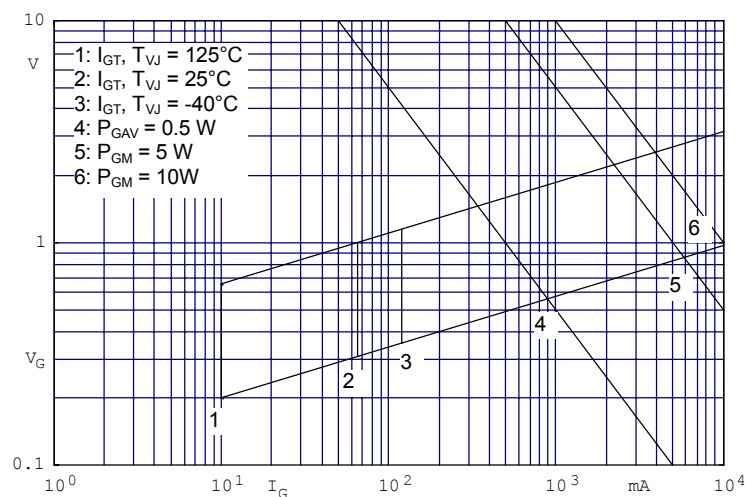


Fig.4 Gate trigger characteristic

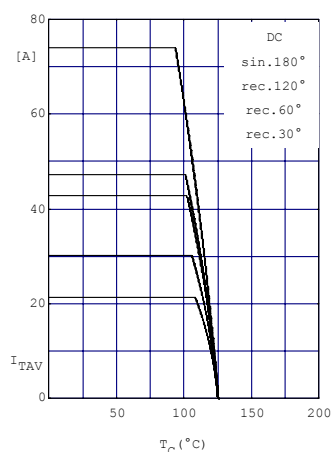


Fig.5 Maximum forward current at case temperature

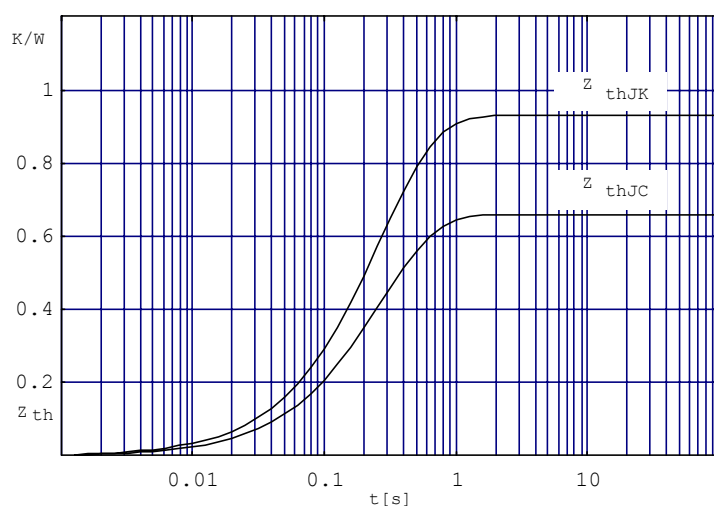


Fig.6 Transient thermal impedance per thyristor or diode (calculated)

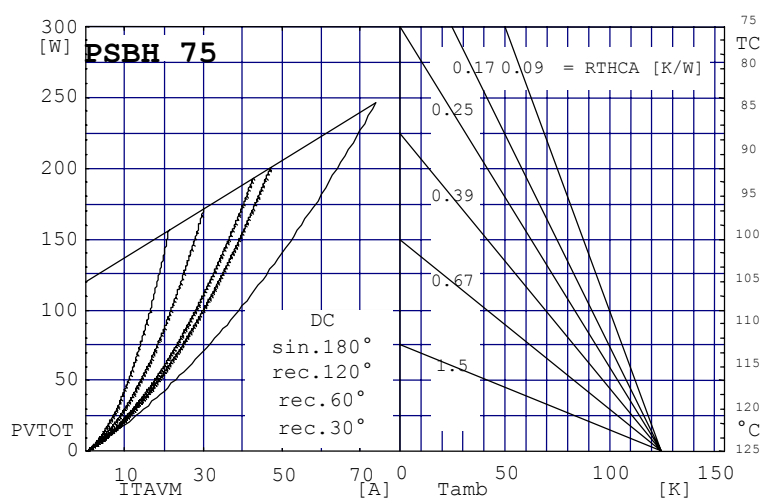


Fig. 7 Power dissipation vs. direct output current and ambient temperature